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NEWBURYPORT, Mass. - June 2, 2000 - Brush Wellman's Electronic Packaging Group (a business unit of Electronic Products Division) has announced the new RF501 pill package to its high performance copper CuPack Power RF product line.

CuPack Products are high performance integrated RF and microwave packages optimized for use with power devices.

The RF501 is an enhanced version of the industry standard outline pill package, 0.230in x 0.360in (5.84mm x 9.14mm). The traditional braze package construction uses a 0.040" thick copper-molybdenum-copper flange for exceptionally low thermal resistance. Additionally, the gold plating process has been optimized to provide superior wirebonding and die-attach for both eutectic and preform applications.

"The RF501 represents an advance on the strategic roadmap Brush Wellman has to exploit the electrical and thermal benefits of copper," said Bob Pomerleau, general manager of Brush Wellman's Electronic Packaging Group. "With this package and others in the developmental stage, we're focusing on the high power dissipation requirements of designers using LDMOS, Si, SiC, GaAs, and other semiconductor materials."

Brush Wellman Inc. is a wholly-owned subsidiary of Brush Engineered Materials Inc. (NYSE:BW). Brush Engineered Materials Inc. headquartered in Cleveland, Ohio, is a manufacturer of engineered materials. The Company supplies worldwide markets with Beryllium Products, Alloy Products, Electronic Products, Precious Metal Products and Engineered Materials Systems.